

Application No. 10/749,059
Amendment "B" dated April 2, 2006
Reply to Office Action mailed January 9, 2006

AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0038] with the following amended paragraph:

[0038] In the case where the polymer-based heat sink portion 152 is intended to make direct contact with the electronic circuitry of the curing device, the polymer-based heat sink portion 152 will preferably not contain electrically conductive metals or other materials (at least on the vicinity of the circuitry) that would cause the polymer-based heat sink portion 152 to short circuit the curing device. The polymer-based heat sink portion 152 may include electrically conductive metals or ceramics so long as it does not directly contact exposed electronic circuitry 160 (*i.e.*, there is any insulating material or gap between the polymer-based heat sink portion 152 and the electronic [circuitry] circuitry 160).